

Amendments to the Claims:

1. (Currently Amended) A method for preparing thin integrated circuits having multiple circuit layers comprising the following ~~acts~~ steps:
forming a first circuit layer with multiple sections on a substrate;
depositing a resin-copper coating on the first circuit layer;
forming a second circuit layer with multiple sections on the resin-copper coating to serve as a topmost circuit layer on the substrate;
electrically connecting the first and second circuit layers;
connecting electronic components to the topmost circuit layer;
applying an encapsulant layer to protect the electronic components; and
removing the substrate to expose the first circuit layer after the step of connecting the electronic components to the topmost circuit layer.
2. (Original) The method as claimed in Claim 1, wherein multiple dimples are defined in the substrate before the first circuit layer is formed on the substrate including the dimples; whereby the first circuit layer at the dimples become protrusions after the substrate is removed.
3. (Currently Amended) The method as claimed in Claim 1, wherein the substrate has a flat top face and the first circuit layer is formed on the flat top face substrate in flat.
4. (Original) The method as claimed in Claim 1, wherein the first and second circuit layers are electronically connected by forming microvias through the resin-copper coating from the first circuit layer to the second circuit layer and; forming a conductive layer on the

second circuit layer into the microvias to connect between the first and second circuit layers.

5. (Original) The method as claimed in Claim 1, wherein the electronic components are connected to the second circuit layer by bonding metal wires between the electronic components and the second circuit layer.
6. (Original) The method as claimed in Claim 2, wherein the electronic components are connected to the second circuit layer by bonding metal wires between the electronic components and the second circuit layer.
7. (Original) The method as claimed in Claim 3, wherein the electronic components are connected to the second circuit layer by bonding metal wires between the electronic components and the second circuit layer.
8. (Original) The method as claimed in Claim 4, wherein the electronic components are connected to the second circuit layer by bonding metal wires between the electronic components and the second circuit layer.
9. (Original) The method as claimed in Claim 1, wherein the electronic components are connected to the second circuit layer by soldering tin balls between the electronic components and the second circuit layer.
10. (Original) The method as claimed in Claim 2, wherein the electronic components are connected to the second circuit layer by soldering tin balls between the electronic components and the second circuit layer.

11. (Original) The method as claimed in Claim 3, wherein the electronic components are connected to the second circuit layer by soldering tin balls between the electronic components and the second circuit layer.
12. (Original) The method as claimed in Claim 4, wherein the electronic components are connected to the second circuit layer by soldering tin balls between the electronic components and the second circuit layer.
13. (Original) The method as claimed in Claim 1, wherein multiple isolating layers are respectively applied to adjacent sections of the exposed first circuit layer after the substrate is removed and multiple tin-paste layers are respectively applied to the first circuit layer between adjacent isolating layers.
14. (Original) The method as claimed in Claim 2, wherein multiple isolating layers are respectively applied to adjacent sections of the exposed first circuit layer after the substrate is removed and multiple tin-paste layers are respectively applied to the first circuit layer between adjacent isolating layers.
15. (Original) The method as claimed in Claim 3, wherein multiple isolating layers are respectively applied to adjacent sections of the exposed first circuit layer after the substrate is removed and multiple tin-paste layers are respectively applied to the first circuit layer between adjacent isolating layers.
16. (Original) The method as claimed in Claim 4, wherein multiple isolating layers are respectively applied to adjacent sections of the exposed first circuit layer after the

substrate is removed and multiple tin-paste layers are respectively applied to the first circuit layer between adjacent isolating layers.

17. (Currently Amended) The method as claimed in Claim 1, wherein the method further comprises the step of following acts forming a third circuit layer on the first circuit layer before forming the topmost circuit layer, before applying the electronic components to the topmost circuit layer;

depositing a resin copper coating on the second circuit layer after the second circuit layer is constructed;

forming a third circuit layer with multiple sections on the resin copper coating to serve as the topmost circuit layer on the substrate;

electronically connecting the second and third circuit layers; and

connecting the electronic components to the topmost circuit layer;

wherein the acts are repeated to increase a consequential circuit layer for each time to achieve multiple circuit layers on the integrated circuit.

18. (New) A method for preparing an integrated circuit having multiple circuit layers comprising the following steps:
forming a first circuit layer on a substrate;
depositing a resin-copper layer on the first circuit layer;
forming a second circuit layer on the resin-copper layer to serve as a topmost circuit layer on the substrate;
bonding an electronic component to the topmost circuit layer;

applying an encapsulant layer to cover the electronic component; and

removing the substrate to expose the first circuit layer after the step of applying the encapsulant layer to cover the electronic component.

19. (New) The method of Claim 18, wherein the electronic component is embedded in the second circuit layer.

20. (New) A method for preparing an integrated circuit having multiple circuit layers comprising the following steps:

forming a first circuit layer on a substrate;

depositing a resin-copper layer on the first circuit layer;

forming a second circuit layer on the resin-copper layer to serve as a topmost circuit layer on the substrate;

bonding an electronic component to the topmost circuit layer;

applying an encapsulant layer to cover the electronic component and all layers above the first circuit layer; and

removing the substrate to expose the first circuit layer after the step of applying the encapsulant layer, wherein the encapsulant layer replaces the substrate to support the integrated circuit.